



MtM+ Technology

M905

Bluetooth 4.2 Low Energy SiP Module

with MCU and integrated antenna

DATASHEET
5th September, 2017

Table of Contents

1	Product Brief	1
2	Features and Applications	2
3	Block Diagram.....	3
4	Technical Specifications	4
4.1	Absolute Maximum Ratings	4
4.2	Operation Condition	4
4.3	Wireless Specifications	4
4.4	Radio Specifications – Bluetooth 4.2 Low Energy	4
4.5	Built-In Antenna Performance	5
4.5.1	Antenna Pattern.....	6
4.5.2	Antenna Design Guide	8
4.6	Power Consumption	12
5	Dimensions	13
6	Pin Assignments	16
7	Recommended Footprint	18
8	Reference Design Circuit	19
9	Recommended Reflow Profile.....	21
10	SiP Module Preparation	22
10.1	Handling	22
10.2	SMT Preparation	22
11	Package Information	23
11.1	Product Marking	23
11.2	Package Information	24
12	Document History	25

1 Product Brief

The SiP module M905 is a small size module with built-in antenna and EMI shielding performance. The module provides full function of Bluetooth 4.2 Low Energy in a tiny module via 52 pins LGA Foot Print. The M905 module provides everything required to create Bluetooth 4.2 Low Energy product with RF, baseband, MCU, qualified Bluetooth v4.2 stack and customer application running on a single IC.

M905 enables ultra-low power connectivity and basic data transfer for applications previously limited by the power consumption, size constraints and complexity of other wireless standards. The low power consumption and excellent radio performance make it the best solution for OEM /ODM customers who require embedded Bluetooth 4.2 Low Energy feature, such as, Home Automation, PAN, sport and fitness watch, mouse, led light bulb etc.

KEY FEATURES

- Bluetooth 4.2 Low Energy Compliant
- ARM® Cortex™-M4 32 bit processor with FPU
- 512 kB programmable flash
- 64 kB RAM
- Built-in antenna
- RF range: up to 100m
- NFC-A tag interface for easy pairing
- TX Power -20 to +4 dBm in 4 dB steps
- RX Sensitivity: -93 dBm
- Ultra-compact package at 6.5x6.5mm

For the software and driver development, we provide extensive technical document and reference software code for the system integration. Hardware evaluation kit and development utilities are ready to applied.

2 Features and Applications

Feature List

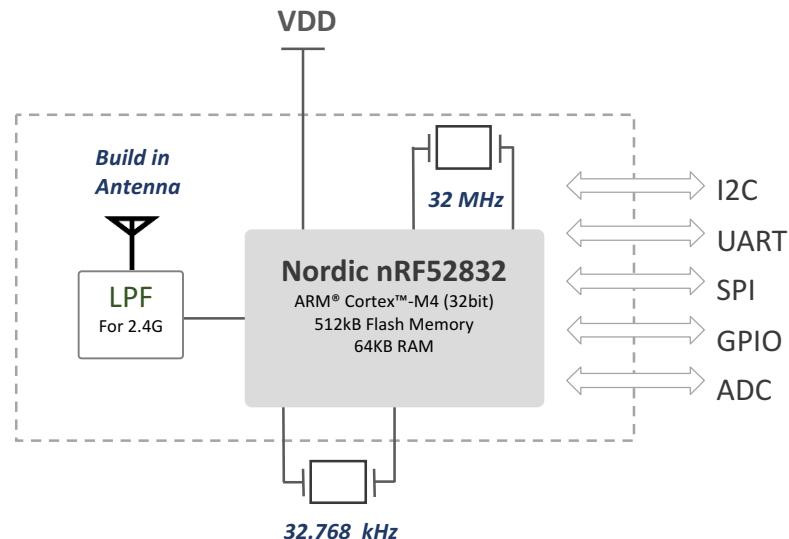
- Multi-protocol with Bluetooth low energy / ANT / 2.4G RF
- Built-in antenna
- 32-bit ARM Cortex M4F processor
- 512kB flash + 64kB RAM
- LGA-52 package, 6.5 x 6.5 x 1.1 mm
- Application development independent from protocol stack
- Programmable output power from +4dBm to -20dBm
- Flexible and configurable 26 pin GPIO
- Simple ON/OFF global power modes
- Digital interfaces including: SPI/2-wire/UART/PDM/I2S
- 12-bit/200KSPS ADC
- 128-bit AES ECB/CCM/AAR co-processor
- Quadrature demodulator
- Low power 32MHz crystal and RC oscillators
- Ultra-lowpower 32kHz crystal and RC oscillators
- Wide supply voltage range (1.7 V to 3.6 V)
- On-chip DC/DC buck converter
- Individual power management for all peripherals

Applications

- IoT
 - Smart home
 - Sensor networks
 - Building automation
 - Industrial
 - Retail
- Personal area networks
 - Health/fitness sensor and monitor devices
 - Medical devices
 - Key-fobs and wrist watches
- Interactive entertainment devices
 - Remote controls
 - Gaming controllers
- Beacons
- A4WP wireless chargers and devices
- Remote control toys
- Computer peripherals and I/O devices
 - Mouse
 - Keyboard
 - Multi-Touch-PAD

3 Block Diagram

There are fully integration module with nRF52832, 32MHz low power crystal. Especially, there is built-in antenna with compart coating.



4 Technical Specifications

Operation and storage condition

4.1 Absolute Maximum Ratings

Item	Description	Value	Unit
Ratings Over Operating Free-Air Temperature Range			
1	Supply voltage	-0.3 to 3.9	V
2	Voltage on any pin	-0.3 to 3.9	V
3	Storage temperature range	-35 to 75	°C
4	Bluetooth RF output (Typ.)	4	dBm

4.2 Operation Condition

Operating Condition	Min	Typical	Max	Unit
VCC	1.7	3.3	3.6	V
Operation ambient temperature range	-20		70	°C

4.3 Wireless Specifications

The M905 module is compliant with the following features and standards:

Features	Description
Bluetooth Standards	Bluetooth core v4.2 Low Energy
Antenna Port	Built-in Antenna
Frequency Band	2.402 – 2.480 GHz

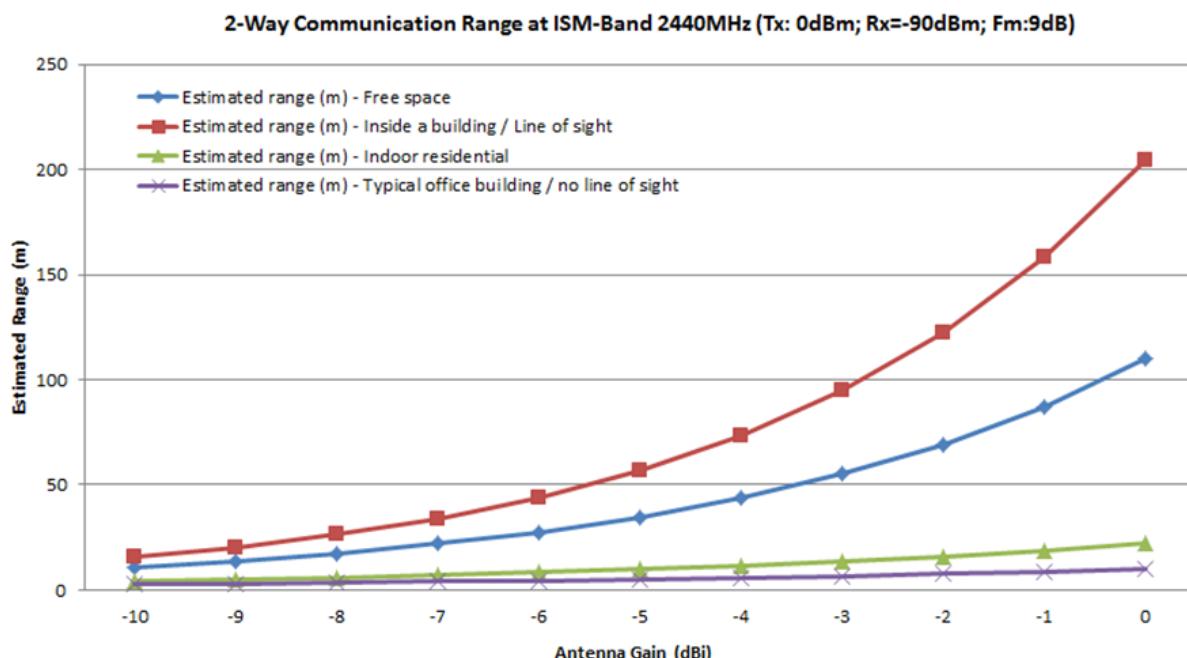
4.4 Radio Specifications – Bluetooth 4.2 Low Energy

Features	Description
Features	Bluetooth core v4.2 Low Energy
Frequency Band	2.402 – 2.480 GHz
Number of selectable sub channels	40 Channels
Modulation	GFSK
Support Rates	<2Mbps
Maximum receive level	-10dBm (with PER<30.8%)

4.5 Built-In Antenna Performance

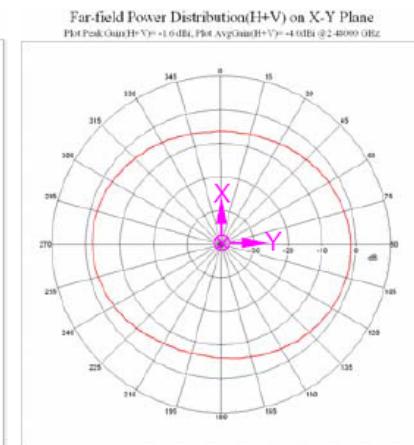
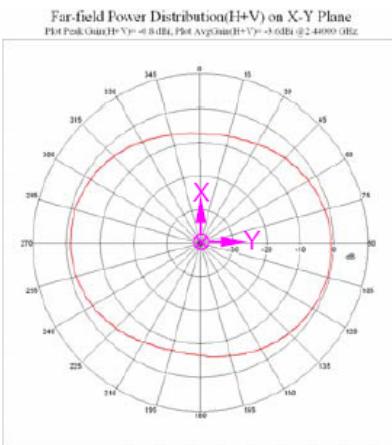
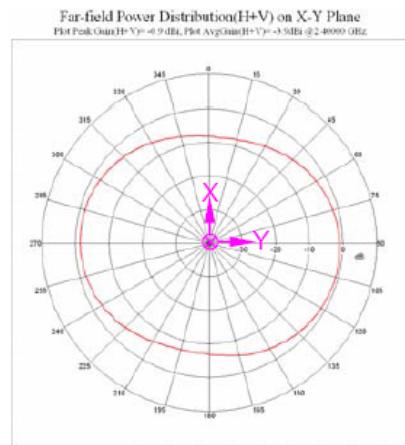
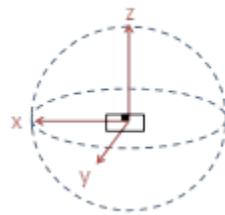
Item	Freq. Band	Gain	Return Loss	VSWR
Spec	2.4~2.5 GHz	>5dBi	<6dB	3 max
Item	Impedance	Polarization	Directivity	Efficiency
Spec	50 ohm	Linear	Omni-Directional	>30%

Antenna Gain Reference

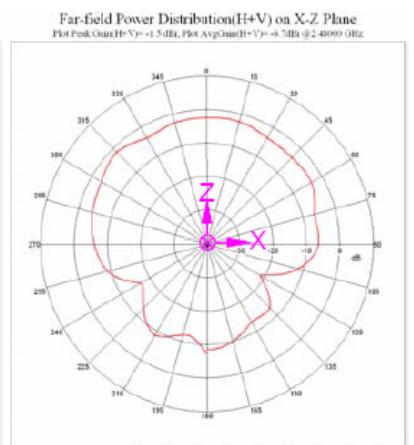
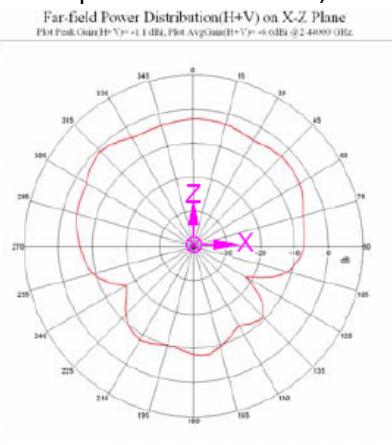
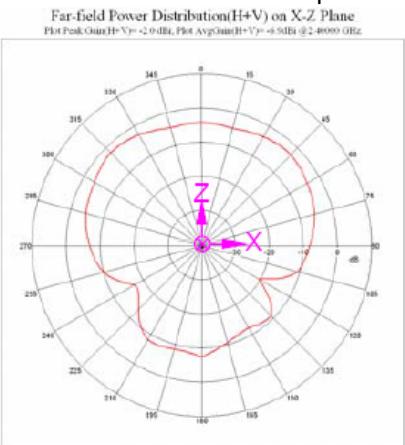


4.5.1 Antenna Pattern

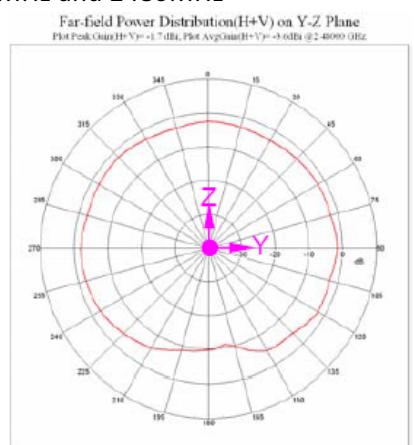
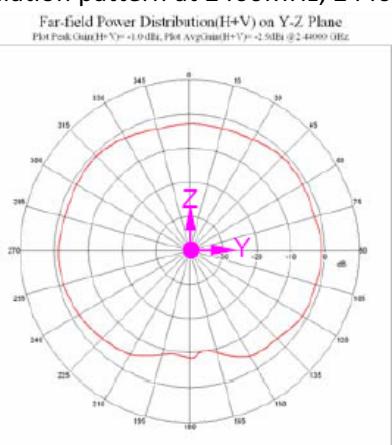
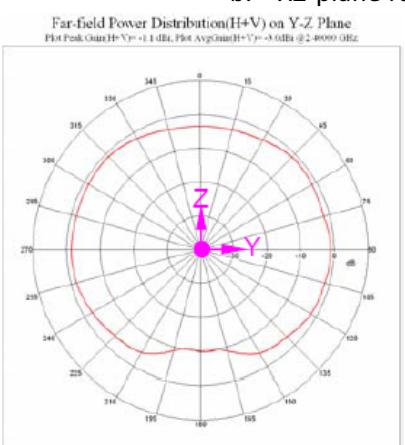
2D Radiation Pattern Plot (Centre Edge)



a. XY-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz

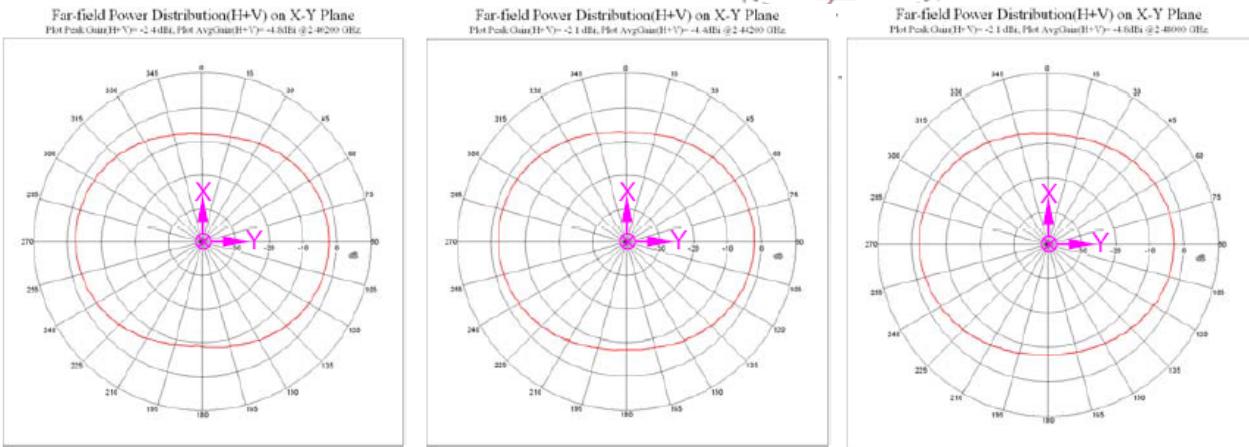


b. XZ-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz

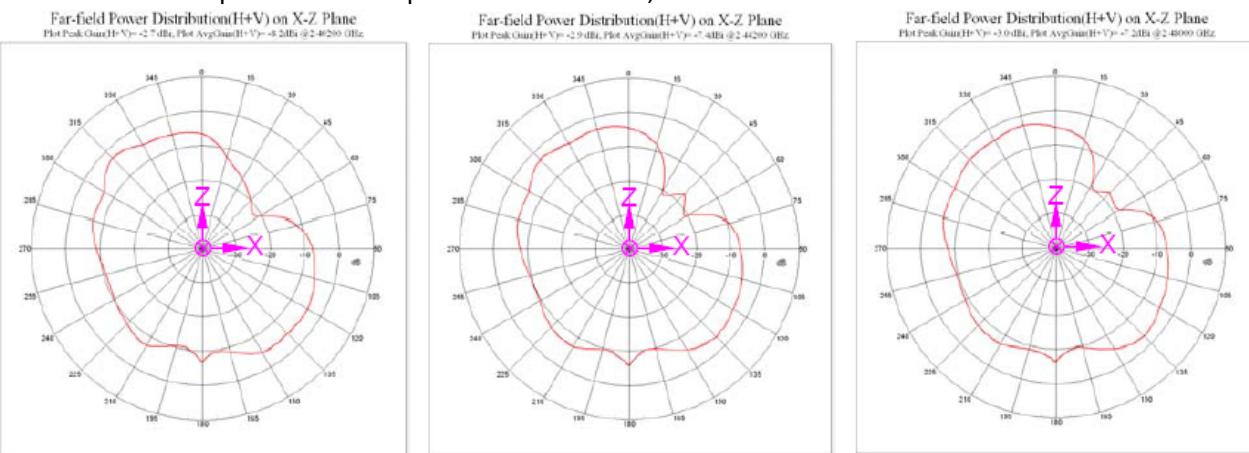


c. YZ-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz

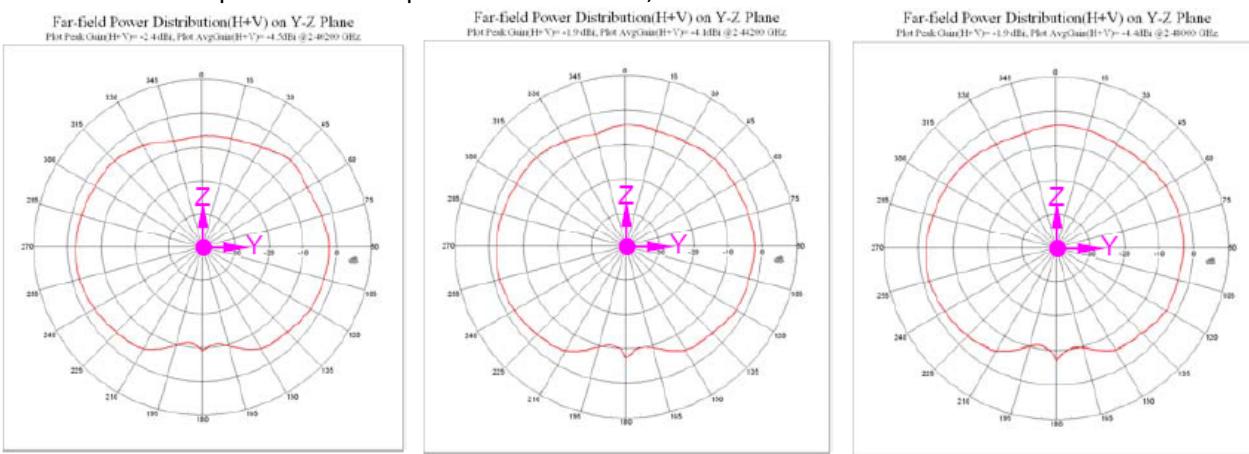
2D Radiation Pattern Plot (Corner Design)



a. XY-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz



b. XZ-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz

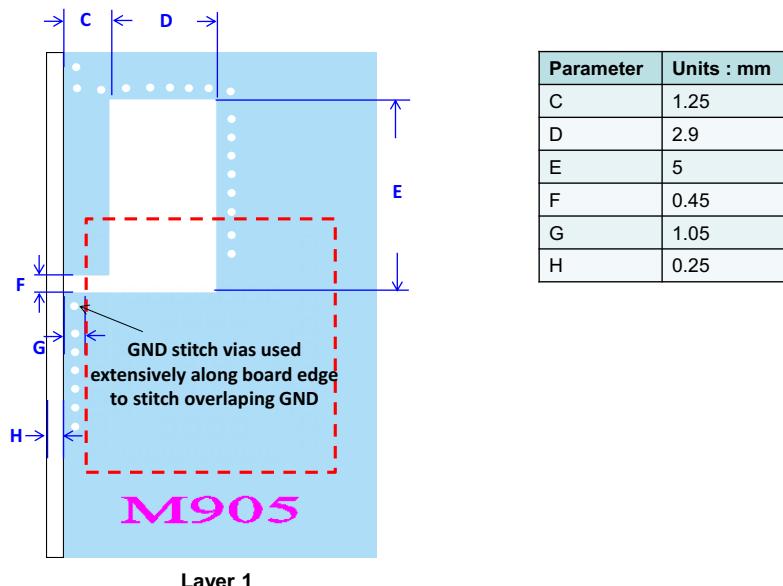
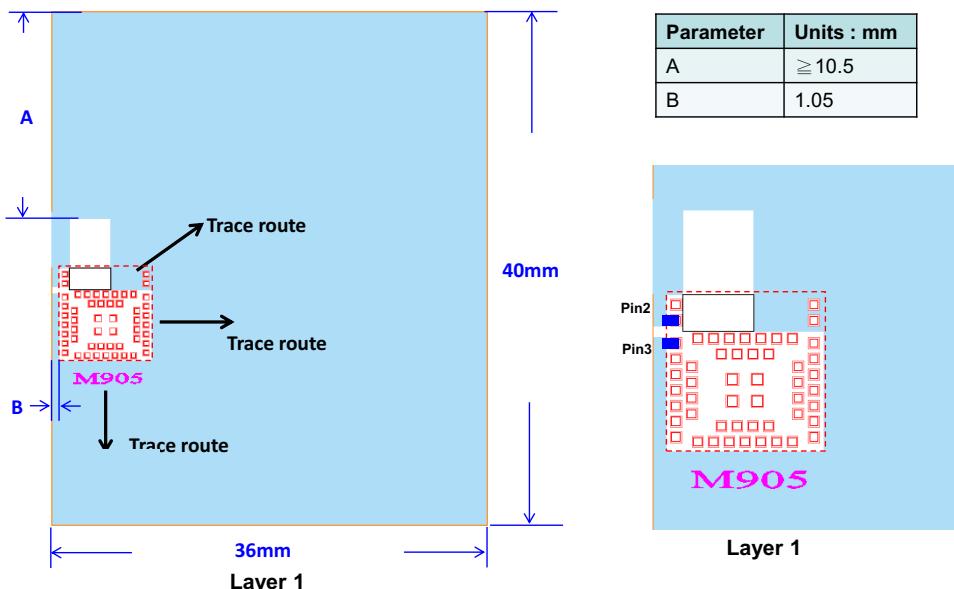


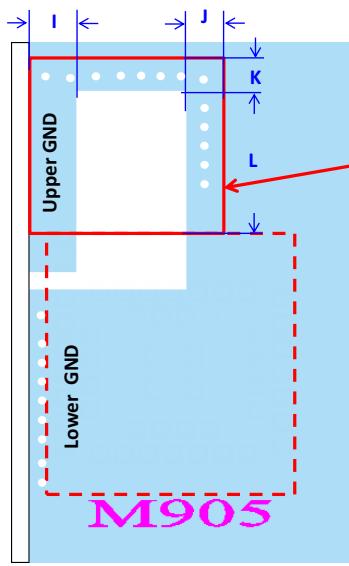
c. YZ-plane radiation pattern at 2400MHz, 2440MHz and 2480MHz

4.5.2 Antenna Design Guide

Center Edge:

- Keep $A \geq 10.5\text{mm}$, $B \geq 0.55\text{mm}$
- Connect Pin 2 to Upper GND, Pin 3 to lower GND
- Don't route signal trace across antenna clearance area
- Recommand that module must be placed at long side.

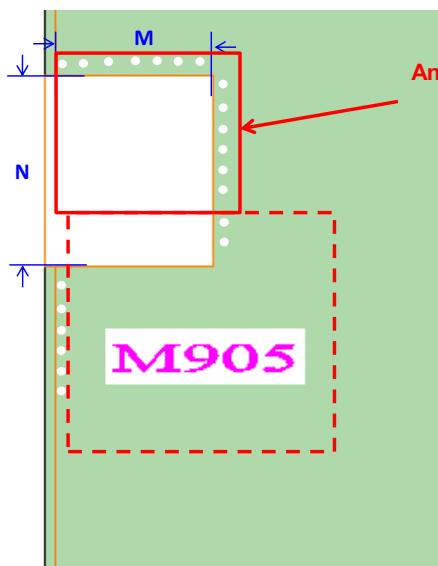




Antenna Clearance Area

Parameter	Units : mm
I	1.25
J	0.5
K	0.5
L	3.5

Layer 1



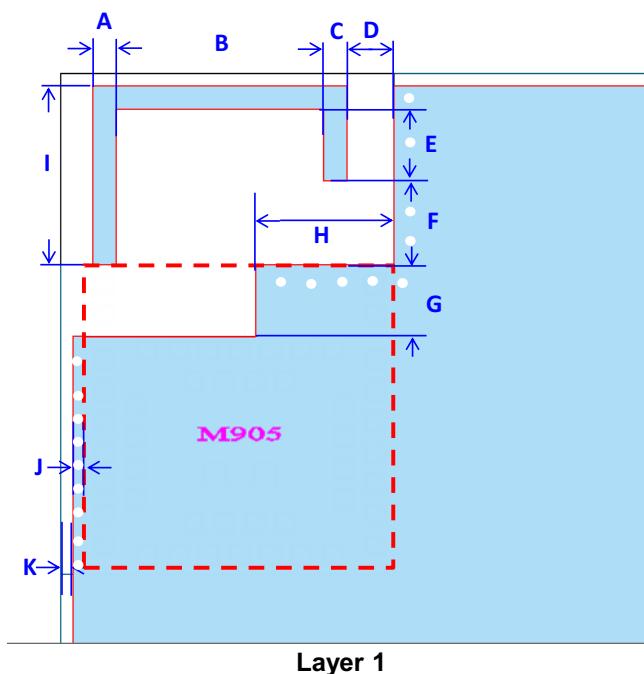
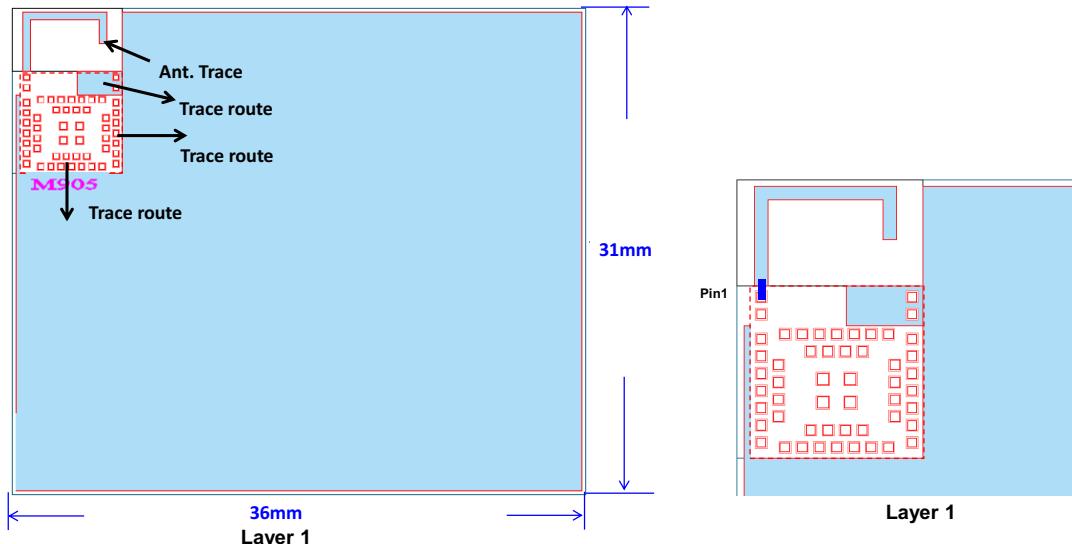
Antenna Clearance Area

Parameter	Units : mm
M	4.15
N	5

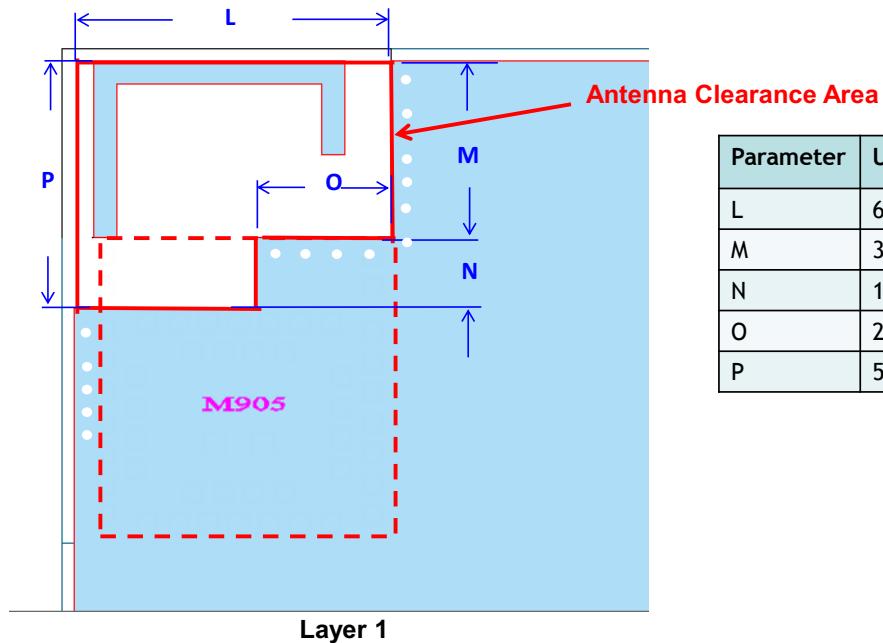
Layer 2,3,4

Option 2: Coner :

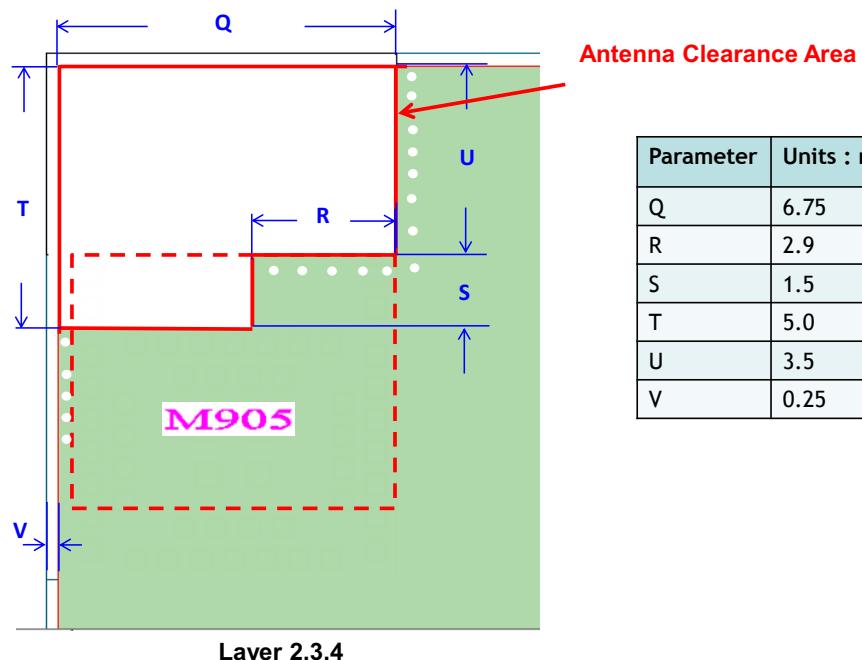
- Connect Pin 1 to Ant. trace
- Don't route signal trace across antenna clearance area



Parameter	Units : mm
A	0.5
B	4.34
C	0.5
D	1
E	1
F	2
G	1.5
H	0.29
I	3.5
J	0.25
K	0.25



Parameter	Units : mm
L	6.75
M	3.5
N	1.5
O	2.9
P	5



Parameter	Units : mm
Q	6.75
R	2.9
S	1.5
T	5.0
U	3.5
V	0.25

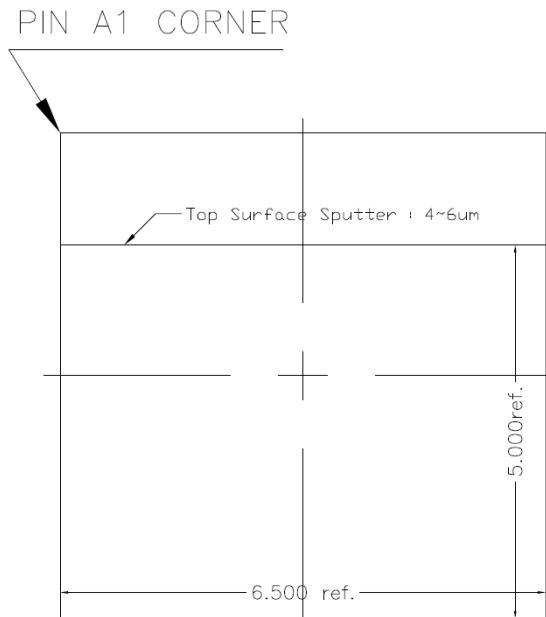
4.6 Power Consumption

Item	Typ.	Units
Tx Mode 0dBm	7.1	mA
Rx Mode @ 1Mb/s	6.5	mA
System On, No RAM retention, Wake on any event	1.2	uA
System On, No RAM retention Wake on reset	1.5	uA
System OFF, Full 64 kB RAM retention, wake on reset	0.7	uA

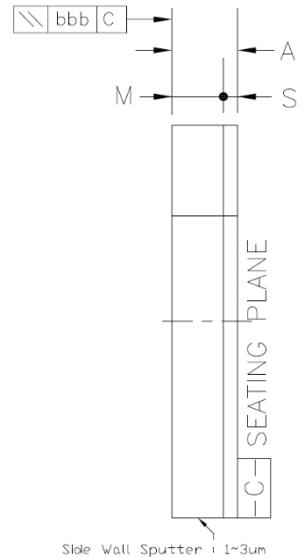
5 Dimensions

The size and thickness of the M905 module are 6.5mm (W) x 6.5mm (L) x 1.2mm (H):

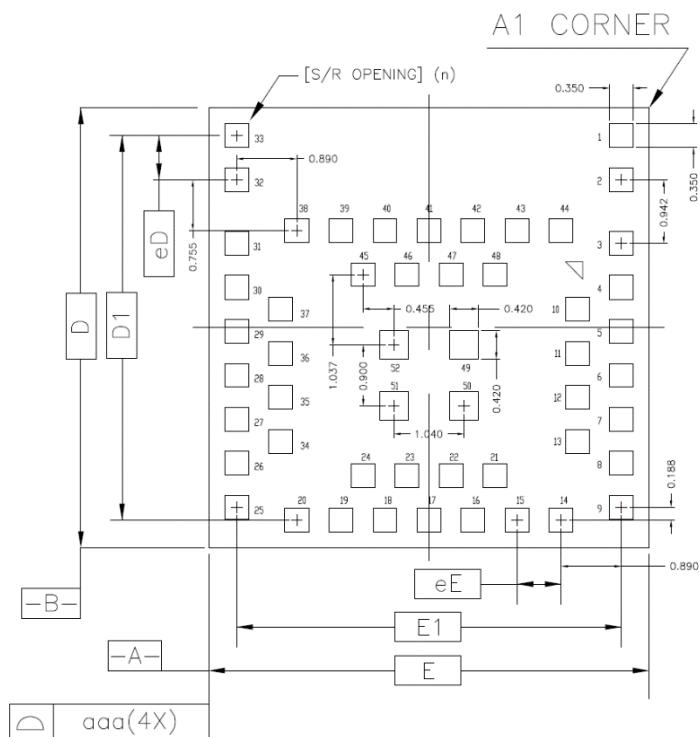
Top-View:



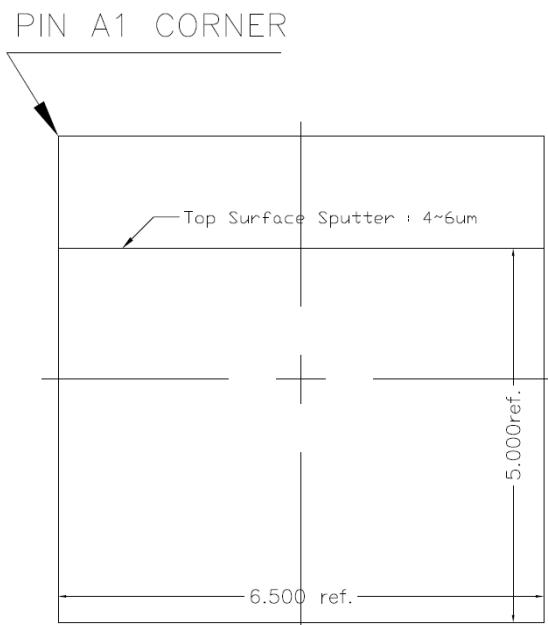
Side-View:



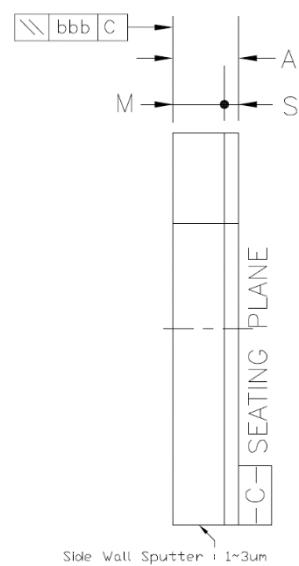
Bottom-View:



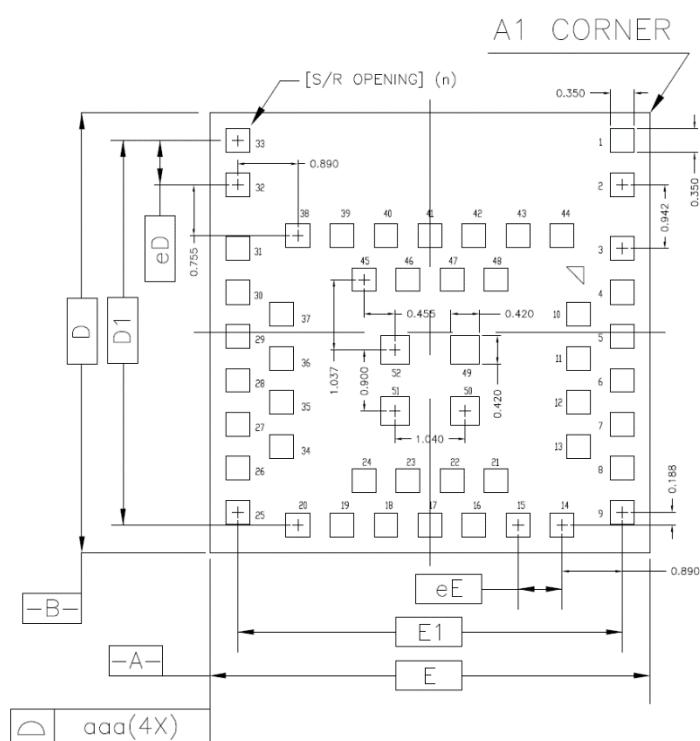
Top-View:



Side-View:



Bottom-View:



Dimensions

	Symbol	Common Dimensions	
Package :		PIM	
Body Size:	X	E	6.500
	Y	D	6.500
Lead Pitch :	X	eE	0.650
	Y	eD	0.650
Total Thickness :	A	1.100±0.100	
Mold Thickness :	M	0.860 Ref.	
Substrate Thickness :	S	0.240 Ref.	
S/R Opening :		0.350*0.350 / 0.420*0.420	
Stand Off :	A1	--- ~ ---	
Ball Width :	b	--- ~ ---	
Package Edge Tolerance :	aaa	0.100	
Mold Flatness :	bbb	0.100	
Coplanarity:	ddd	---	
Ball Offset (Package) :	eee	---	
Ball Offset (Ball) :	fff	---	
Lead Count :	n	52	
Edge Lead Center to Center :	X	E1	5.680
	Y	D1	5.680

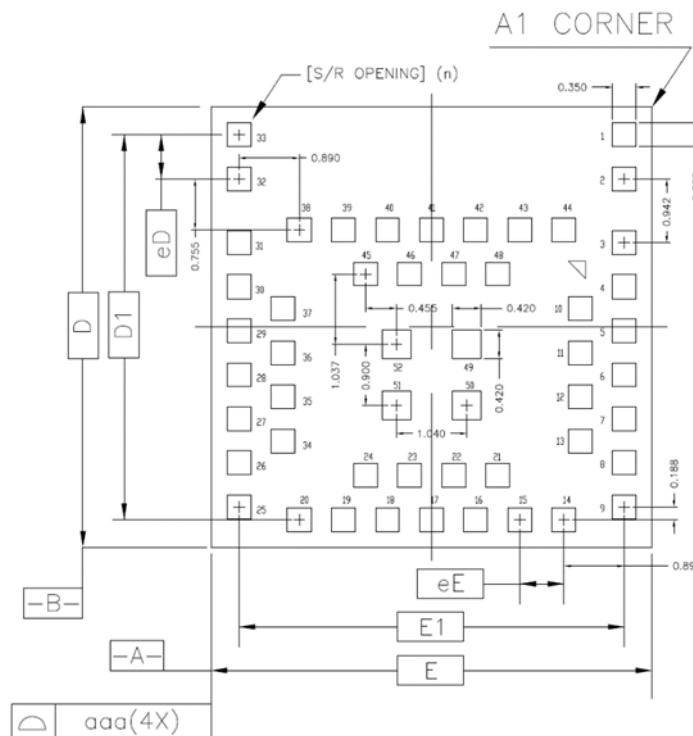
6 Pin Assignments

Pin number	Pin name	Pin function	Description
1	Antenna Leg	RF	Antenna Option 2
2	GNDA1	RF	Antenna Option 1
3	GNDA2	RF	Antenna Option 1
4	GND	Power	Ground (0V)
5	ANT	RF	Signal-ended radio antenna connection
6	RF	RF	Conducted radio connection
7	GND	Power	Ground (0V)
8	GND	Power	Ground (0V)
9	VDD	Power	Power supply
10	GND	Power	Ground (0V)
11	GND	Power	Ground (0V)
12	P0.21/nRESET	Digital I/O	General purpose I/O pin. Configurable as system RESET pin
13	P0.14/TRACEDATA[3]	Digital I/O	General purpose I/O pin. Trace port output
14	P0.15/TRACEDATA[2]	Digital I/O	General purpose I/O pin. Trace port output
15	P0.16/TRACEDATA[1]	Digital I/O	General purpose I/O pin. Trace port output
16	P0.18/TRACEDATA[0]	Digital I/O	General purpose I/O pin. Trace port output
17	P0.00/XL1	Digital I/O Analog input	General purpose I/O pin. Connection for 32.768kHz crystal (LFXO)
18	P0.01/XL2	Digital I/O Analog input	General purpose I/O pin. Connection for 32.768kHz crystal (LFXO)
19	P0.03/AIN1	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
20	P0.02/AIN0	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
21	P0.09/NFC1	Digital I/O NFC input	General purpose I/O pin. NFC antenna connection
22	P0.10/NFC2	Digital I/O NFC input	General purpose I/O pin. NFC antenna connection
23	P0.05/AIN3	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
24	P0.04/AIN2	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
25	P0.31/AIN7	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
26	P0.30/AIN6	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
27	P0.29/AIN5	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
28	P0.28/AIN4	Digital I/O Analog input	General purpose I/O pin. SAADC/COMP/LPCOMP input
29	P0.27	Digital I/O	General purpose I/O pin
30	P0.25	Digital I/O	General purpose I/O pin
31	P0.26	Digital I/O	General purpose I/O pin
32	GND	Power	Ground (0V)
33	GND	Power	Ground (0V)
34	P0.11	Digital I/O	General purpose I/O pin
35	P0.19	Digital I/O	General purpose I/O pin
36	P0.22	Digital I/O	General purpose I/O pin
37	P0.23	Digital I/O	General purpose I/O pin
38	P0.24	Digital I/O	General purpose I/O pin
39	SWDCLK	Digital input	Serial wire debug clock input for debug and programming
40	SWDIO	Digital I/O	Serial wire debug I/O for debug and programming
41	GND	Power	Ground (0V)
42	GND	Power	Ground (0V)

Pin number	Pin name	Pin function	Description
43	GND	Power	Ground (0V)
44	GND	Power	Ground (0V)
45	P0.20/TRACECLK	Digital I/O	General purpose I/O pin. Trace port clock output
46	GND	Power	Ground (0V)
47	GND	Power	Ground (0V)
48	GND	Power	Ground (0V)
49	GND	Power	Ground (0V)
50	GND	Power	Ground (0V)
51	GND	Power	Ground (0V)
52	GND	Power	Ground (0V)

7 Recommended Footprint

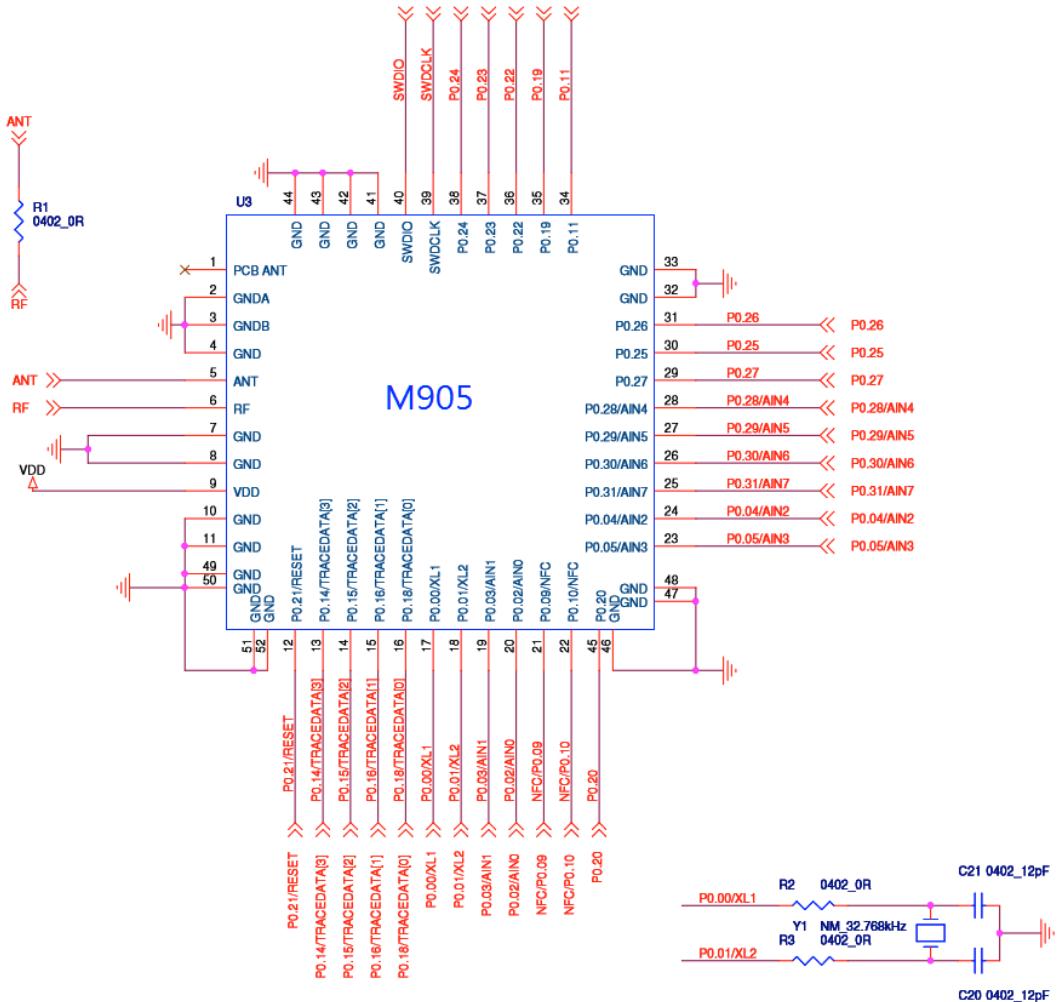
Suggest on PCB: SMD (1:1)



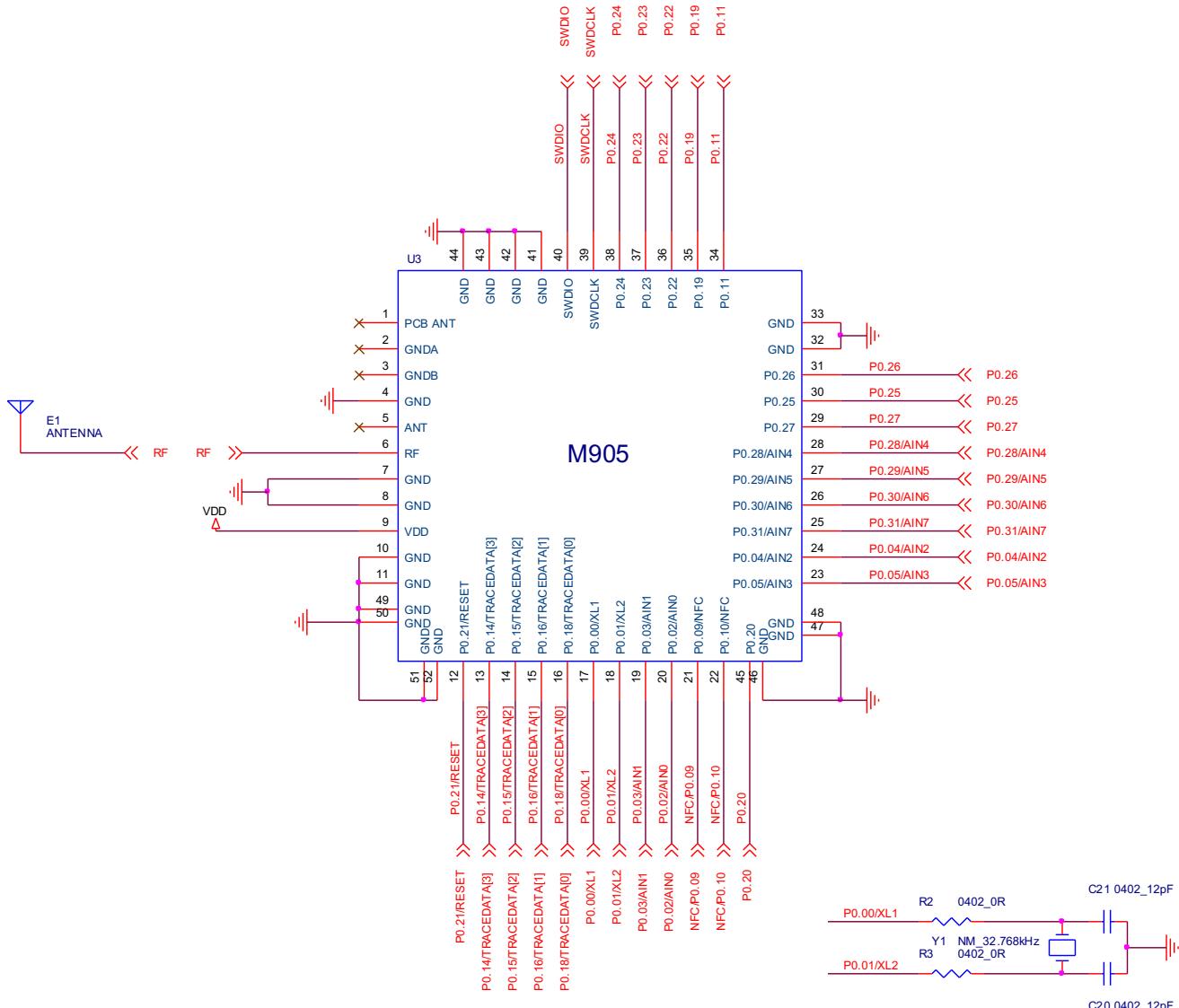
	Symbol	Common Dimensions	
Package :		PIM	
Body Size:	X	E	6.500
	Y	D	6.500
Lead Pitch :	X	eE	0.650
	Y	eD	0.650
Total Thickness :	A	1.100±0.100	
Mold Thickness :	M	0.860 Ref.	
Substrate Thickness :	S	0.240 Ref.	
S/R Opening :		0.350*0.350 / 0.420*0.420	
Stand Off :	A1	--- ~ ---	
Ball Width :	b	--- ~ ---	
Package Edge Tolerance :	aaa	0.100	
Mold Flatness :	bbb	0.100	
Coplanarity:	ddd	---	
Ball Offset (Package) :	eee	---	
Ball Offset (Ball) :	fff	---	
Lead Count :	n	52	
Edge Lead Center to Center :	X	E1	5.680
	Y	D1	5.680

8 Reference Design Circuit

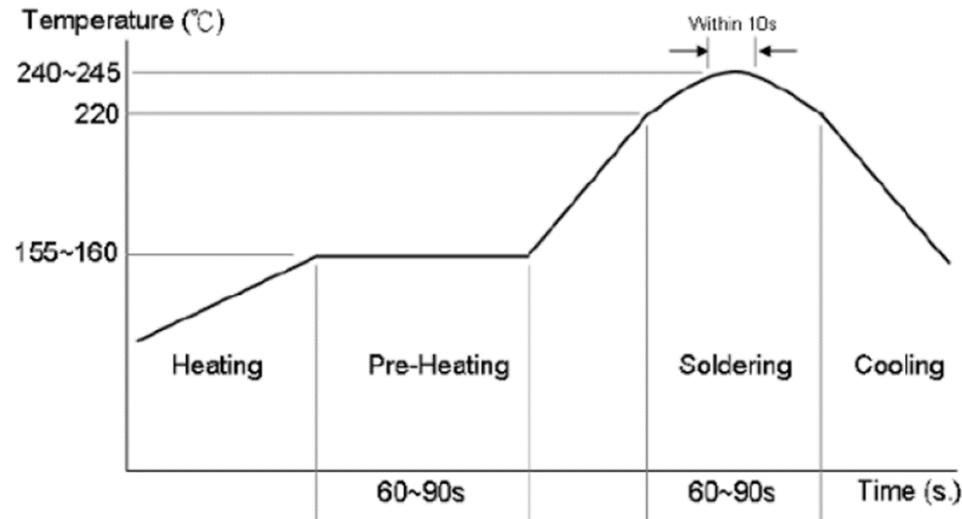
AoP Design



External Antenna Design



9 Recommended Reflow Profile



Profile Condition

- a. Suitable for Lead-Free solder
- b. Between 155~160°C: 60~90 sec.
- c. Above 220°C: 60~90 sec.
- d. Peak Temperature: 240~245 (<10 sec.)

10 SiP Module Preparation

10.1 Handling

Handling the module must wear the anti-static wrist strap to avoid ESD damage. After each module is aligned and tested, it should be transport and storage with anti-static tray and packing. This protective package must be remained in suitable environment until the module is assembled and soldered onto the main board.

10.2 SMT Preparation

1. Calculated shelf life in sealed bag: 6 months at <40°C and <90% relative humidity (RH).
2. Peak package body temperature: 250°C.
3. After bag was opened, devices that will be subjected to reflow solder or other high temperature process must.
 - a. Mounted within: 72 hours of factory conditions <30°C /60% RH.
 - b. Stored at \leq 10% RH with N2 flow box.
4. Devices require baking, before mounting, if:
 - a. Package bag does not keep in vacuumed while first time open.
 - b. Humidity Indicator Card is >10% when read at $23\pm5^\circ\text{C}$.
 - c. Expose at 3A condition over 8 hours or Expose at 3B condition over 24 hours.
5. If baking is required, devices may be baked for 12 hours at $125\pm5^\circ\text{C}$.

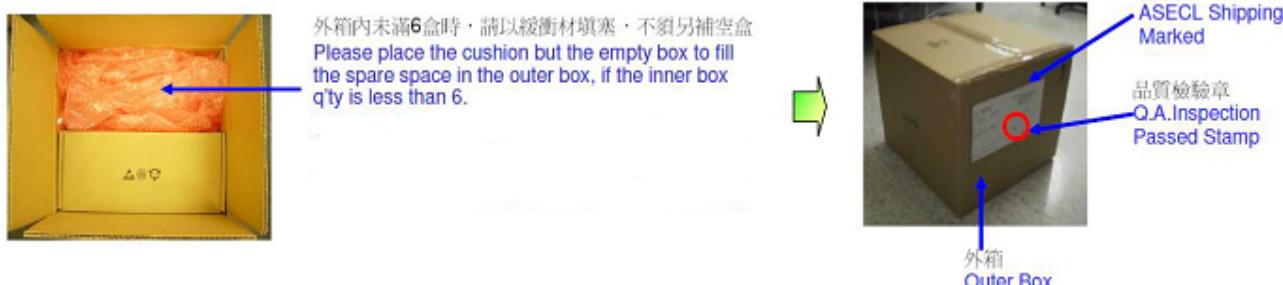
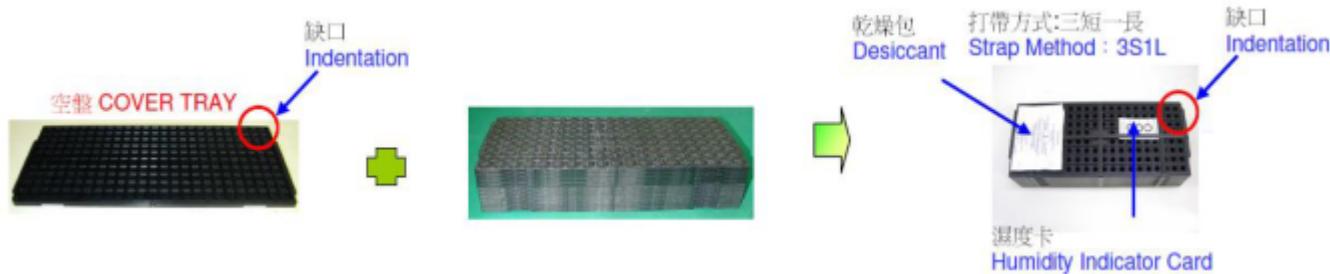
11 Package Information

11.1 Product Marking



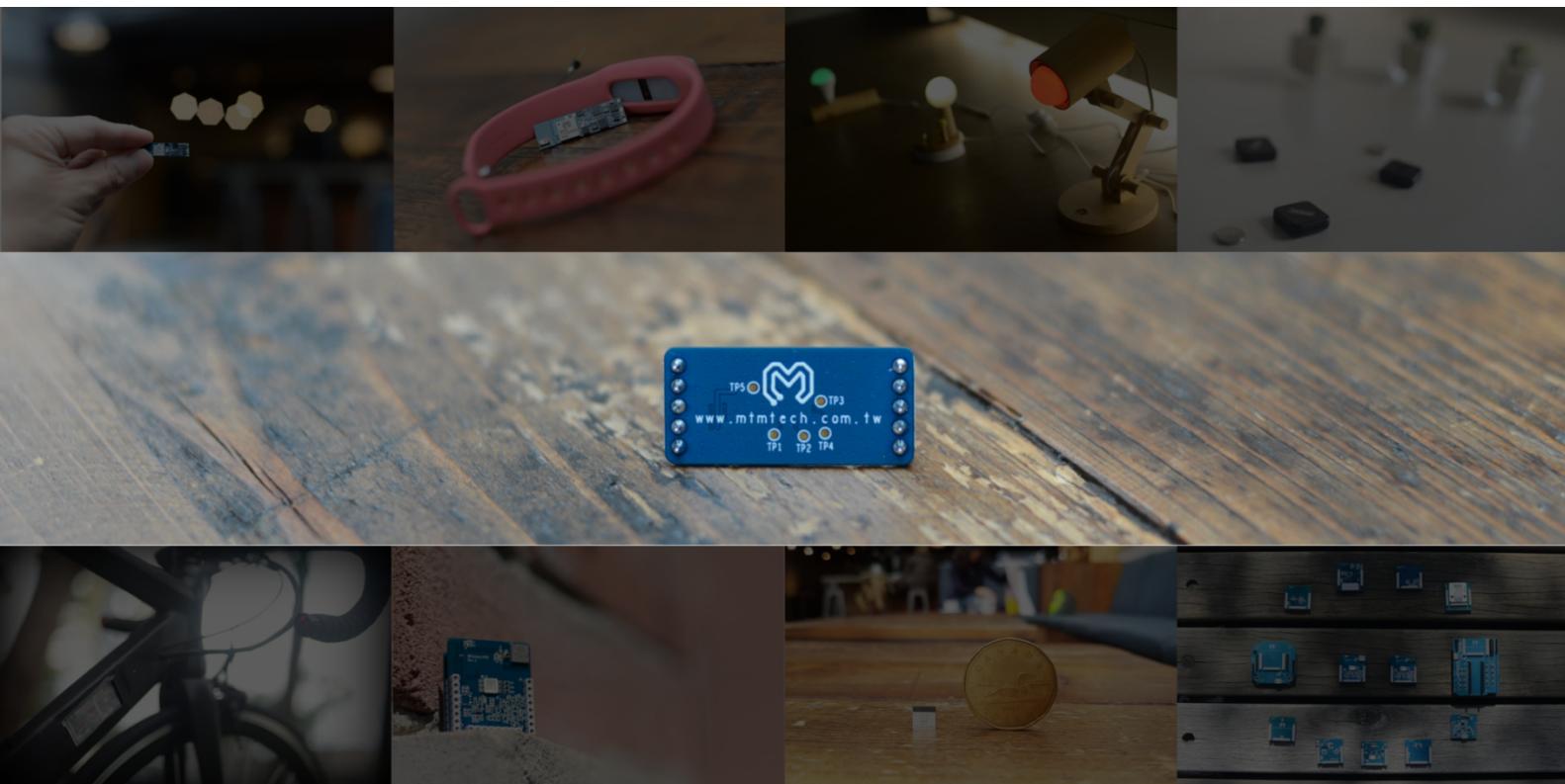
- Line 1: M905 (Model Name)
- Line 2: YYWW (Date Code)
- Line 3: 2AJ9P-M905 (FCC ID)

11.2 Package Information



12 Document History

Date	Modifications	Version
Jan. 23, 2016	Preliminary Version	1.0
May. 08, 2016	AoP Design Guide & Antenna Pattern Update	1.1
Sep. 05, 2017	Rebrand as MtM+ Technology	1.2



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